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**Scope**

- **Biosensors**
  - Lab-on-chip
  - Miniaturized diagnostic
  - Novel bioelectric sensing
  - Nanophotonics/THz Sensing

- **Bioelectronics**
  - Biomedical signal processing
  - Body area sensor networks
  - Circuits for biomedical applications/devices
  - Flexible electronics
  - Implantable electronics

- **Biomedical Devices**
  - Bio-imaging technology
  - Biocompatible materials and packaging
  - Implantable medical devices
  - Prosthesis and neural probes
  - Surgical robots

- **MEMS/NEMS**
  - MEMS/NEMS sensors and actuators
  - Energy harvesting technology
  - MEMS/NEMS for biomedical applications
  - Microfluidics for biomedical applications

**Submission Deadline:** June 30, 2020

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Editorial Department of *Sensors and Materials*
MYU K.K.
1-23-3-303 Sendagi, Bunkyo-ku, Tokyo 113-0022, Japan
Tel: +81-3-3827-8549, Fax: +81-3-3827-8547
E-mail: myukk@myu-inc.jp